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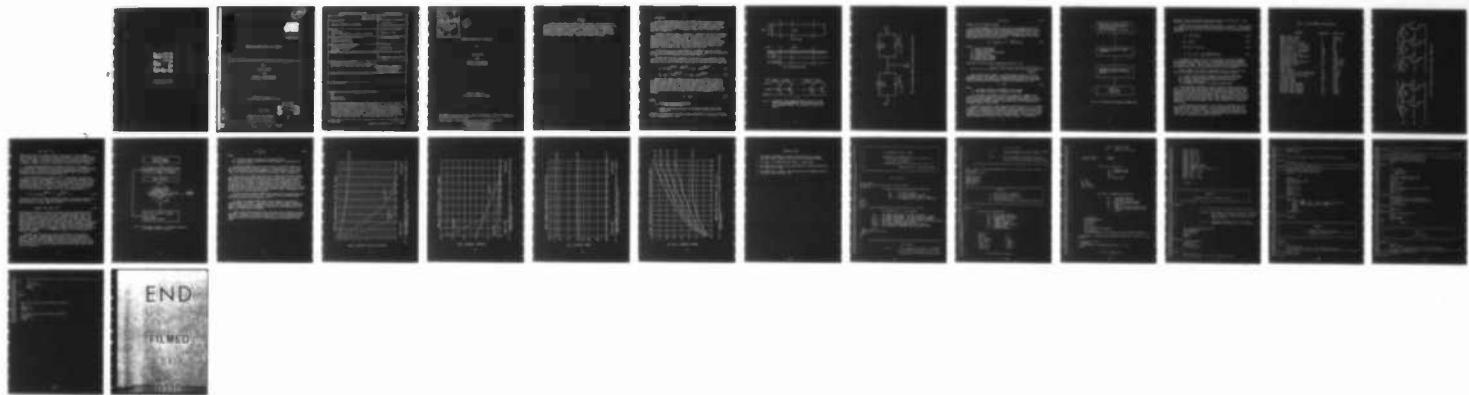
NUMERICAL MODELING OF THE MOSBJT(U) HAWAII UNIV AT
MANOA HONOLULU DEPT OF ELECTRICAL ENGINEERING
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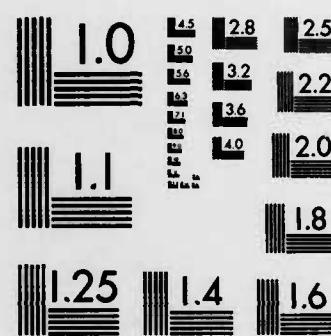
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NUMERICAL MODELING OF THE MOSBJT

by

David Okada

and

James W. Holm-Kennedy
Principal Investigator

ONR Final Report II
Contract No. N-0014-76-C-1081

July 1983

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NUMERICAL MODELING OF THE MOSBJT*

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ONR Final Report II
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*The MOSBJT was proposed by Prof. James W. Holm-Kennedy, Electrical Engineering Department, University of Hawaii.

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ABSTRACT

A totally merged MOSFET and BJT has been proposed. The device exhibits complicated non-linear characteristics under certain operating conditions. Due to the distributed character of this novel merged device, a straightforward lumped device approach is not adequate. A distributed model is proposed and analyzed using numerical techniques. The active device area is shown to be affected by bias and contributes to the non-linear character of the characteristics under suitable conditions. Several gate shapes are treated.

1. Introduction

A novel merged MOSFET/BJT device (the MOSBJT) was previously described [1]. The device is fully merged which results in a distributed behavior. The MOSFET channel can be used as an emitter or as a collector. In order to analyze the device, a distributed FET BJT model must be used. Approximate analytical models have been treated [2] and will be reported elsewhere and is similar to that described in Report III.

The MOSBJT numerical model is based upon an equivalent circuit for the MOSBJT. The construction of the equivalent circuit is as follows: First the distributed bipolar injection into the MOSBJT channel is modeled by dividing the device length-wise into many equal sections (refer to Fig. 3.1a, b). Each section is then represented by a n-channel metal oxide semiconductor field effect transistor (MOSFET) connected to a npn bipolar junction transistor (BJT) resulting in the equivalent circuit shown in Fig. 3.1c. Built into this circuit model is the assumption that minority carrier transport occurs vertically.

The npn BJTs and the n-channel MOSFETs in the MOSBJT equivalent circuit (Fig. 3.1c) are represented by their classical DC models. These are the Ebers-Moll BJT model [3] and the distributed analysis MOSFET model [4].

The Ebers-Moll BJT model represents the npn BJT with the equivalent circuit shown in Fig. 3.2. From the equivalent circuit the following expressions for the collector current (I'_C) and the base current (I'_B) for the transistor are determined.

$$I'_C = \alpha_F I_{ES} [e^{qV_{BE}/KT} - e^{qV_{BC}/KT}] - I_{CS}(1 - \alpha_R)[e^{qV_{BC}/KT} - 1] \quad (3.1)$$

$$I'_B = I_{ES}(1 - \alpha_F)[e^{qV_{BE}/KT} - 1] + I_{CS}(1 - \alpha_R)[e^{qV_{BC}/KT} - 1] \quad (3.2)$$

The Ebers-Moll model parameters ($\alpha_F, \alpha_R, I_{ES}, I_{CS}$) for the BJT elements in the MOSBJT circuit model are extracted from the experimental data of a typical rectangular MOSBJT operating with the entire channel active. The magnitude of the BJT collector current for a particular section (I_{Cx}) is proportional to the collector area of that section. The proportionality constant is determined by normalizing the area of each section to the total collector (channel) area. This factor is then used to scale the total collector current expressed by Eq. (3.1) yielding:

$$I_{Cx} = K_x I'_C \quad (3.3)$$

where

$$K_x = \frac{\text{collector area of the } x^{\text{th}} \text{ section}}{\text{total collector area}}$$

$x \equiv$ integer specifying the section of the numerical MOSBJT model being referred to

Similarly an expression for the base current contribution of a particular section, x can be expressed by Eq. (3.4).

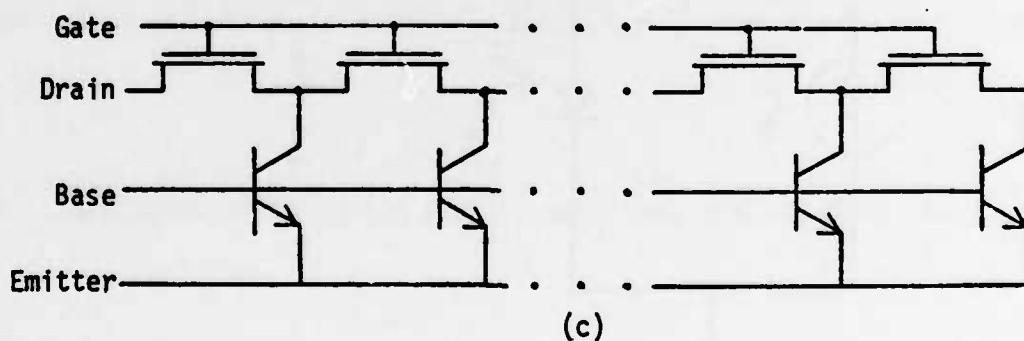
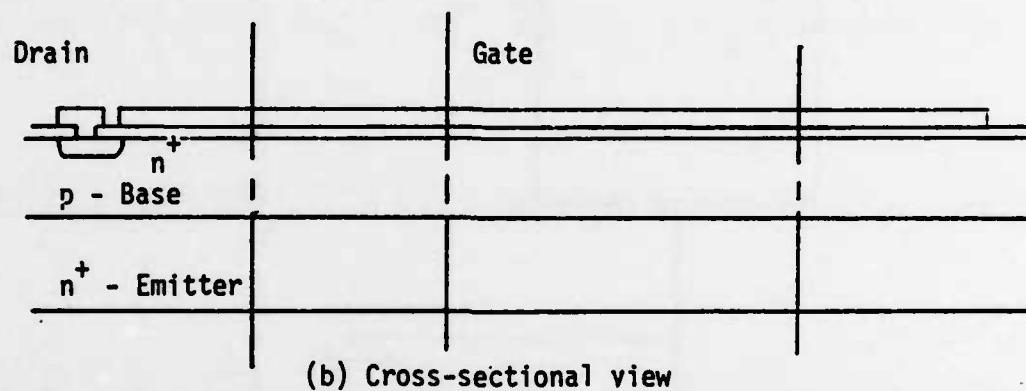
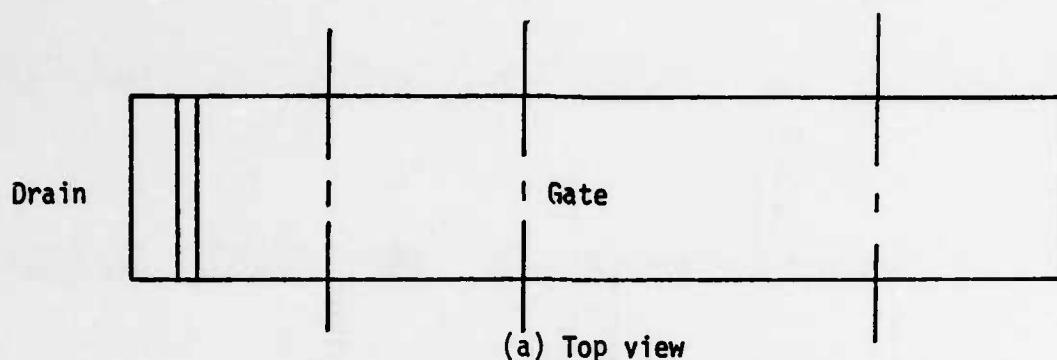


Fig. 3.1 Development of the MOSBJT equivalent circuit. (a) Top view of a rectangular MOSBJT. (b) Cross-sectional view of a rectangular MOSBJT. (c) Equivalent circuit of the MOSBJT.

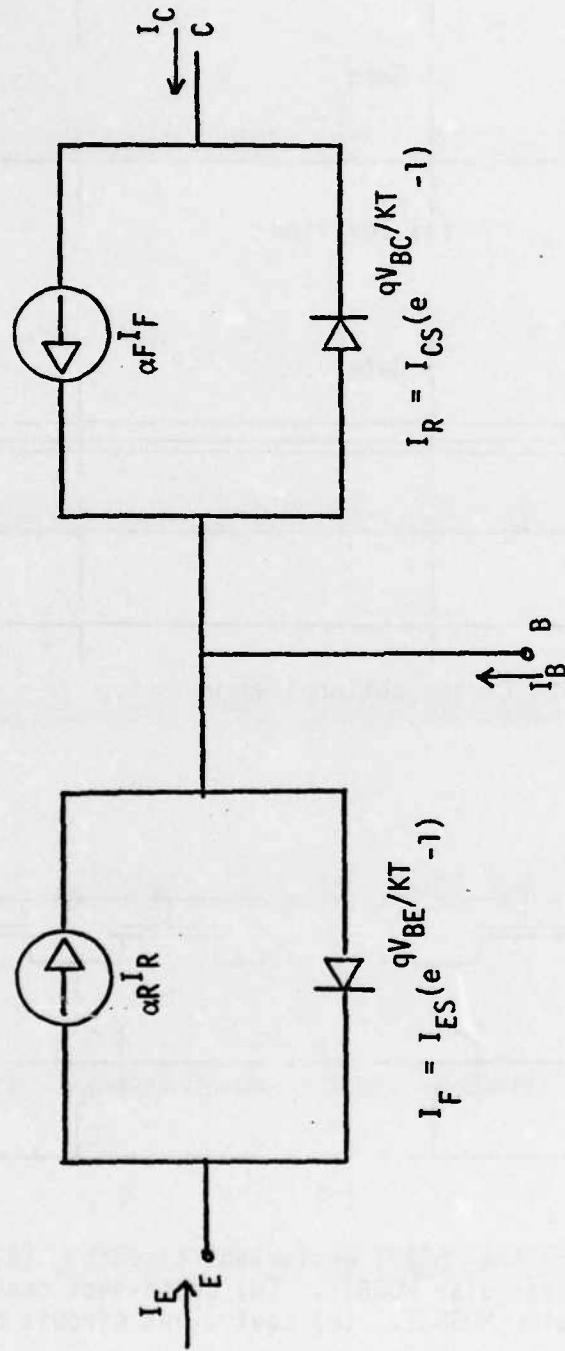


Fig. 3.2 Ebers-Moll model of a npn bipolar junction transistor

$$I_{Bx} = K_x I'_B \quad (3.4)$$

where K_x and x are defined as above.

The n-channel MOSFETs are modeled with the distributed MOSFET model and the gradual channel approximation [3]. Incorporated into the MOSFET model are the assumptions that the channel voltage can be approximated by a half of the sum of the source and drain voltages ($\frac{1}{2}(V_S + V_D)$) and that the channel length is much greater than the depletion region at the drain. The MOSFET model yields the following expression for the drain current (I_D).

$$I_D = \mu_n \frac{W}{L} C'_ox (V_G - V_T - \frac{V_D - V_S}{2})(V_D - V_S) \quad (3.5)$$

where

- W = width of the channel
- L = length of the channel
- μ_n = electron mobility in the channel
- V_T = threshold voltage .
- V_D = applied drain voltage
- V_S = applied source voltage
- V_G = applied gate voltage

Solving Eq. (3.5) for the drain voltage (V_D) yields Eq. (3.6).

$$V_D = V_S + V_G - V_T - \sqrt{(V_S + V_G - V_T)^2 - (2(V_G - V_T) + V_S^2 + \frac{2(V_G - V_T)I_DL}{\mu_n W C'_ox})} \quad (3.6)$$

The n-channel MOSFET elements in the MOSBJT circuit model (Fig. 3.1c) are represented by Eqs. (3.5) and (3.6). Since each MOSFET represents a section of the MOSBJT channel, the length of each MOSFET should be equal to the total MOSBJT channel length divided by the number of sections as expressed by Eq. (3.7).

$$L' = L/N \quad (3.7)$$

where

- L' = the channel length for the MOSFET circuit elements
- N = the number of sections in the MOSBJT circuit model

For a rectangular gate MOSBJT the width of the gate of the MOSFET circuit element will simply be equal to the width of the MOSBJT gate. MOSBJT's with non-rectangular gate geometries are easily simulated by representing each section with a rectangular MOSFET of length L/N and width equal to the average width of the MOSBJT channel in that section.

The computer algorithm, listed in Appendix A and outlined in Fig. 3.3, consists of 4 modules. The function of these modules, labeled A through D, are as follows: In Module A, the MOSBJT material properties, device characteristics, geometry, and operating bias are defined and various required parameters calculated. The purpose of module B is to determine the extent of channel cut-off. Next in module C the spatial dependence of voltage and current along the channel is determined and

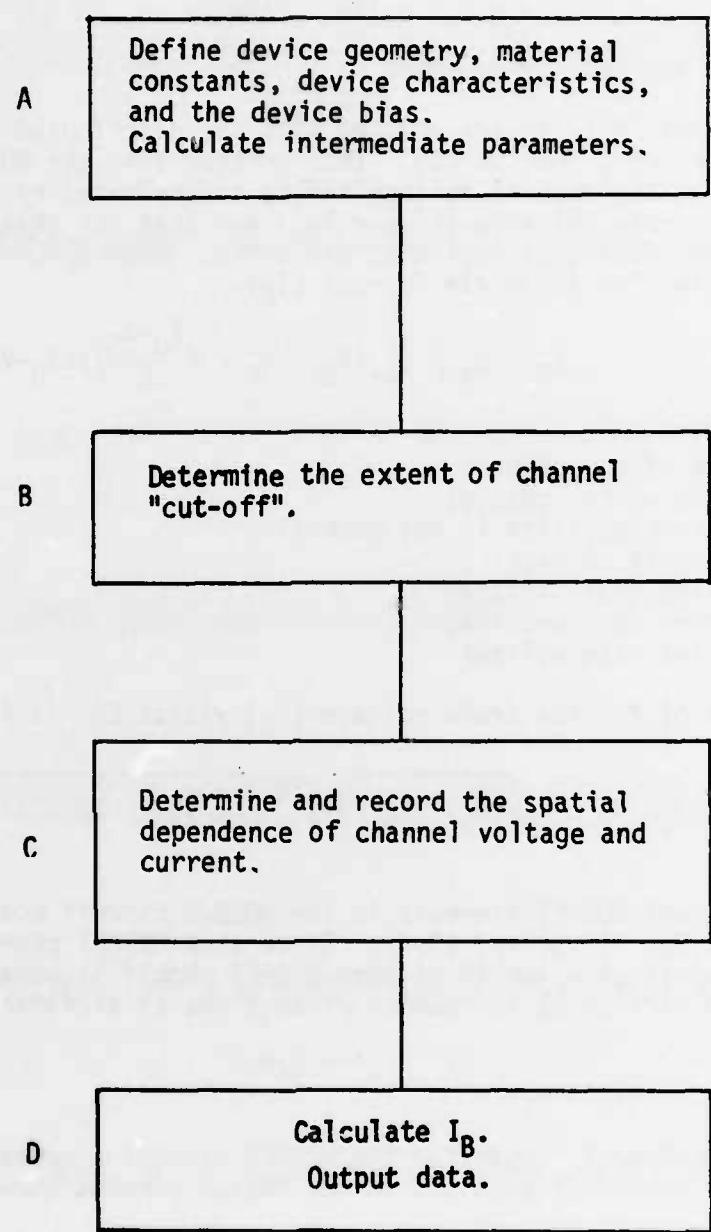


Fig. 3.3 Flow chart of the numerical MOSBJT model

recorded. Finally in module D the base current (I_B) is calculated and its value along with the rest of the data is printed or plotted.

In module A, the numerical MOSBJT model parameters are defined. These parameters are listed in Table 3.1 along with their typical values. Values for ϕ_p , C'_ox , V_{FB} , V_T are determined by evaluating the following expressions derived from conventional MOS theory [3].

$$\phi_p = - \frac{KT}{q} \ln(N_a/N_i) \quad (3.8)$$

$$C'_ox = \epsilon_{ox}/T_{ox} \quad (3.9)$$

$$V_{FB} = \phi_M - \phi_S - Q_{ss}/C'_ox \quad (3.10)$$

$$V_T = V_{fb} + 2|\phi_p| + \frac{1}{C'_ox} \sqrt{2\epsilon_{sq}N_a(2|\phi_p|-V_{BE})} \quad (3.11)$$

A substantial portion of the iterative algorithm of the numerical MOSBJT model is contained in modules B and C. In these modules the spatial dependence of the MOSBJT's channel voltage and current are determined for a given device bias (V_{DE} , V_{BE} , and V_G). Once the channel voltage and current profiles are known the terminal drain current (I_D) and base current (I_B) can be determined.

The basic MOSBJT circuit model is shown again in Fig. 3.4 with the various nodes, node voltages, and currents labeled with the following notation:

- X \equiv integer indicating the X^{th} section of the numerical MOSBJT model
- I_{MX} \equiv current flowing through the MOSFET located in the X^{th} section
- I_{CX} \equiv collector current for the BJT located in the X^{th} section
- V_X \equiv voltage at the X^{th} node
- N \equiv the number of sections for the numerical MOSBJT model

A simple approach to determine the node voltages and currents would be to start at the drain where the voltage is known and then calculate the node voltage and current moving from node to node in the direction away from the drain. This approach does not yield a solution because finding V_N (the voltage at the node adjacent to the drain) requires that I_{MN} be known. I_{MN} is equal to the sum of the BJT collector currents at all other nodes. These collector currents are in turn dependent on their respective node voltages. The interdependence of node voltages and currents lead to the development of an iterative approach for the numerical MOSBJT model.

In this approach an initial guess is first made of the voltage (V_1) at the node furthest from the drain (node 1). Next, I_C , can be solved for using the expression for the collector current of a BJT obtained from the Ebers-Moll BJT model (Eq. (3.3)). The current flowing through the MOSFET interconnecting nodes 1 and 2, (I_M) is equal to I_C . A general expression relating the node currents, (Eq. (3.12)) is derived with Kirchoff's current law.

Table 3.1 Typical MOSBJT Device Parameters

Parameter	Nomenclature	Typical Value
MOSBJT channel length	L	3.68E-3 M
MOSBJT channel width	W	2.96E-3 M
Number of sections in model	N	100
Gate voltage w.r.t. the emitter	V_G	30V
Drain voltage w.r.t. the emitter	V_{DE}	20V
Base voltage w.r.t. the emitter	V_{BE}	0.38V
Metal work function (Al)	ϕ_M	4.1ev
Semiconductor work function (Si)	ϕ_S	4.9ev
Oxide permittivity	ϵ_{ox}	3.45E-11 F/M
Semiconductor permittivity (Si)	ϵ_s	1.04E-10 F/M
Semiconductor doping	N_a	1.5E16 cm ⁻³
Temperature	T	300°K
Oxide thickness	t_{ox}	1.2E-7 M
Electric potential of the semiconductor	ϕ_p	-0.358V.
Oxide capacitance per unit area	C_{ox}'	2.88E-4 F
Flatband voltage	V_{FB}	-1.08V
Threshold voltage	V_T	1.72V
Ebers-Moll model parameter	α_F	0.9615
Ebers-Moll model parameter	α_R	0.9975
Ebers-Moll model parameter	I_{ES}	1.04E-8
Ebers-Moll model parameter	I_{CS}	1.002E-8

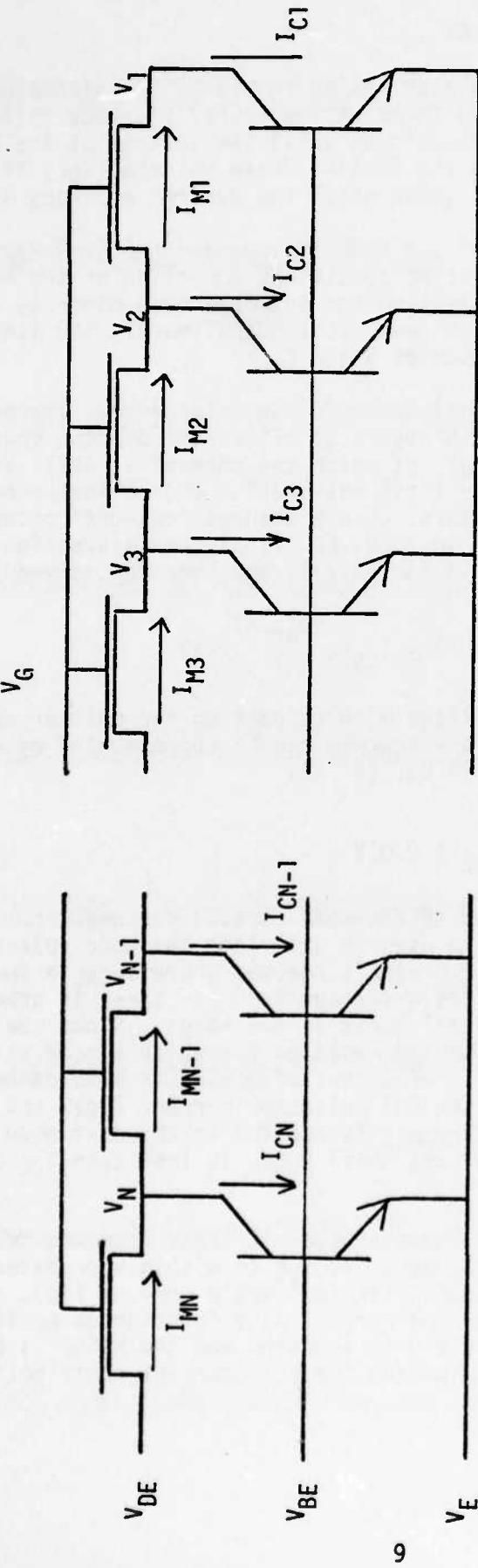


Fig. 3.4 Equivalent circuit for the numerical MOSBJT model

$$I_{MX} = I_{MX-1} + I_{CX} \quad (3.12)$$

Knowing V_1 and I_M , V_2 is then calculated, using Eq. (3.6) in which a MOSFET's drain voltage (V_{X+1}) is expressed in terms of the MOSFET's source voltage (V_X) and drain current (I_{MX}). This process continues until the voltage at the drain (V_{DCAL}) is found. If V_{DCAL} is not equal to the applied drain voltage (V_{DE}) iterative adjustments are made to the initial guess until the desired accuracy is achieved.

From the basic understanding of the MOSBJT's operation [Final Report I] it is known that under certain operating conditions a portion of the MOSBJT channel may be "cut-off" - incapable of collecting the injected base minority carriers. To incorporate channel "cut-off" into the numerical MOSBJT model, the iterative algorithm is partitioned into two modules B and C.

In module B the extent of channel "cut-off" is determined. The algorithm contained in module B is diagrammed in Fig. 3.5. First the minimum channel voltage with respect to the emitter (V_{CHEMIN}), at which the channel is still active as a collector is found. This is done by first solving for the collector-base voltage (V_{BC}) at which channel "cut-off" occurs. Since channel "cut-off" occurs when the BJT collector current (I_{CX}) is equal to zero, Eq. (3.3), the expression for I_{CX} can be set equal to zero, as shown in Eq. (3.13), and then V_{BC} solved for.

$$0 = I_{CX} = K_X F_I_{ES} (e^{\frac{qV_{BE}}{KT}} - 1) - I_{CS} (e^{\frac{qV_{BC}}{KT}} - 1) \quad (3.13)$$

The sum $V_{BC} + V_{BE}$ is the channel voltage with respect to the emitter necessary for channel "cut-off" to occur. Therefore V_{CHEMIN} can be approximated by adding a small voltage to this sum as shown in Eq. (3.14).

$$V_{CHEMIN} = V_{BC} + V_{BE} + 0.01V \quad (3.14)$$

After V_{CHEMIN} is found it is applied to the node located furthest from the drain. Equation (3.3), (3.6), and (3.12) are used to calculate the node voltages and currents along the channel until the drain is reached where $V_{DCAL} = V_{N+1}$. Then V_{DCAL} is compared with the applied drain voltage V_{DE} . If V_{DCAL} is greater than V_{DE} the implication is that the initial guess is too large. Since the voltage applied to node 1 was V_{CHEMIN} (the minimum voltage for which a node will be "active"), node 1 must be biased into "cut-off." The "cut-off" node is modeled by setting the node voltage (V_1) to ($V_{BC} + V_{BE}$) and the BJT collector current (I_{C1}) and the MOSFET current (I_{M1}) equal to zero. Then V_{CHEMIN} is applied to the next node (node 2) and the process is repeated. This continues until V_{DCAL} is less than V_{DE} upon which module C is executed.

In module C the voltage at the "active" node furthest from the drain is adjusted until V_{DCAL} is approximately equal to V_{DE} to within a predetermined accuracy. When this occurs the MOSBJT's terminal drain current (I_D), given by I_M and the MOSBJT's channel voltage and current as a function of position along the channel are recorded. Next module D is executed and the MOSBJT's base current (I_B) is calculated. I_B is found by summing the base current contributions of each section as shown below.

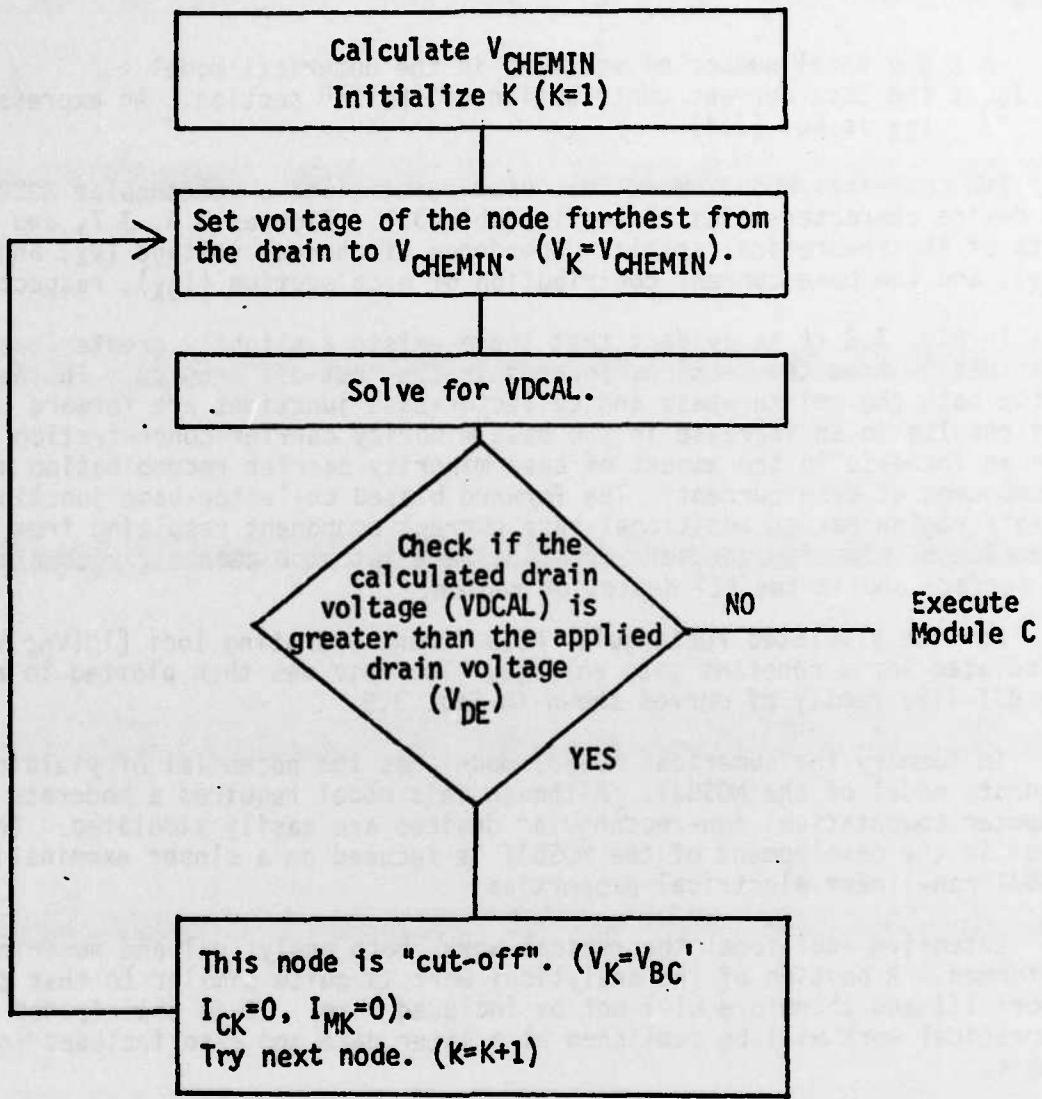


Fig. 3.5 Flow chart of module B. This module determines the extent of channel "cut-off".

$$I_B = \sum_{X=1}^N I_{BX} \quad (3.15)$$

where

N \equiv the total number of sections in the numerical model
 I_{BX} \equiv the base current contribution of the X^{th} section. An expression for I_{BX} is Eq. (3.4).

The numerical MOSBJT model was used to simulate a rectangular MOSBJT with the device characteristics listed in Table 3.1. Figures 3.6, 3.7, and 3.8 are plots of the theoretical spatial dependence of channel voltage (V_X) and current (I_{MX}), and the base current contribution of each section (I_{BX}), respectively.

In Fig. 3.8 it is evident that there exists a slightly greater base current contribution from the sections located in the "cut-off" region. In the "cut-off" region both the emitter-base and collector-base junctions are forward biased. This results in an increase in the base minority carrier concentration and therefore an increase in the amount of base minority carrier recombination which is a component of base current. The forward biased collector-base junction of the cut-off region has an additional base current component resulting from the "reverse" injection of minority carriers from the base into the channel, recombination at the MOS surface and in the FET depletion region.

For the simulated rectangular MOSBJT many operating loci [$I_D(V_{DE}, V_G, I_B)$] were calculated for a constant gate voltage. The data was then plotted to produce the BJT-like family of curves shown in Fig. 3.9.

In summary the numerical MOSBJT model has the potential of yielding an accurate model of the MOSBJT. Although this model requires a moderate amount of computer computation, non-rectangular devices are easily simulated. The current level in the development of the MOSBJT is focused on a closer examination of the MOSBJT non-linear electrical properties.

Extensive additional theoretical work, both analytical and numerical has been performed. A portion of the analytical work is quite similar to that described in Report III and therefore will not be included here. It is anticipated that this theoretical work will be published at a later date and also included in a Ph.D. Thesis.

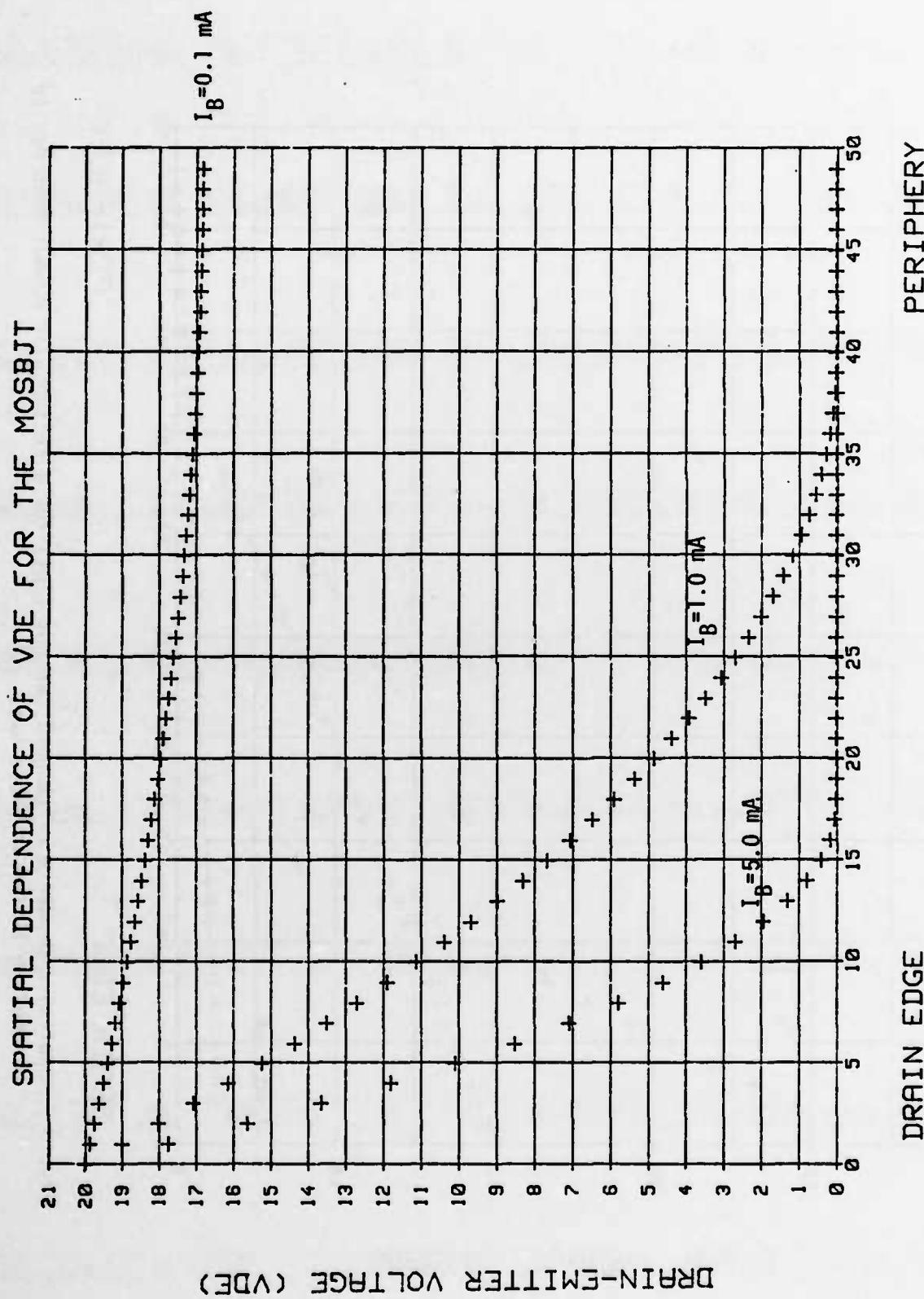


Fig. 3.6 Spatial dependence of channel-emitter voltage (V_x) for a rectangular MOSBJT with device parameters listed in Table 3.1.

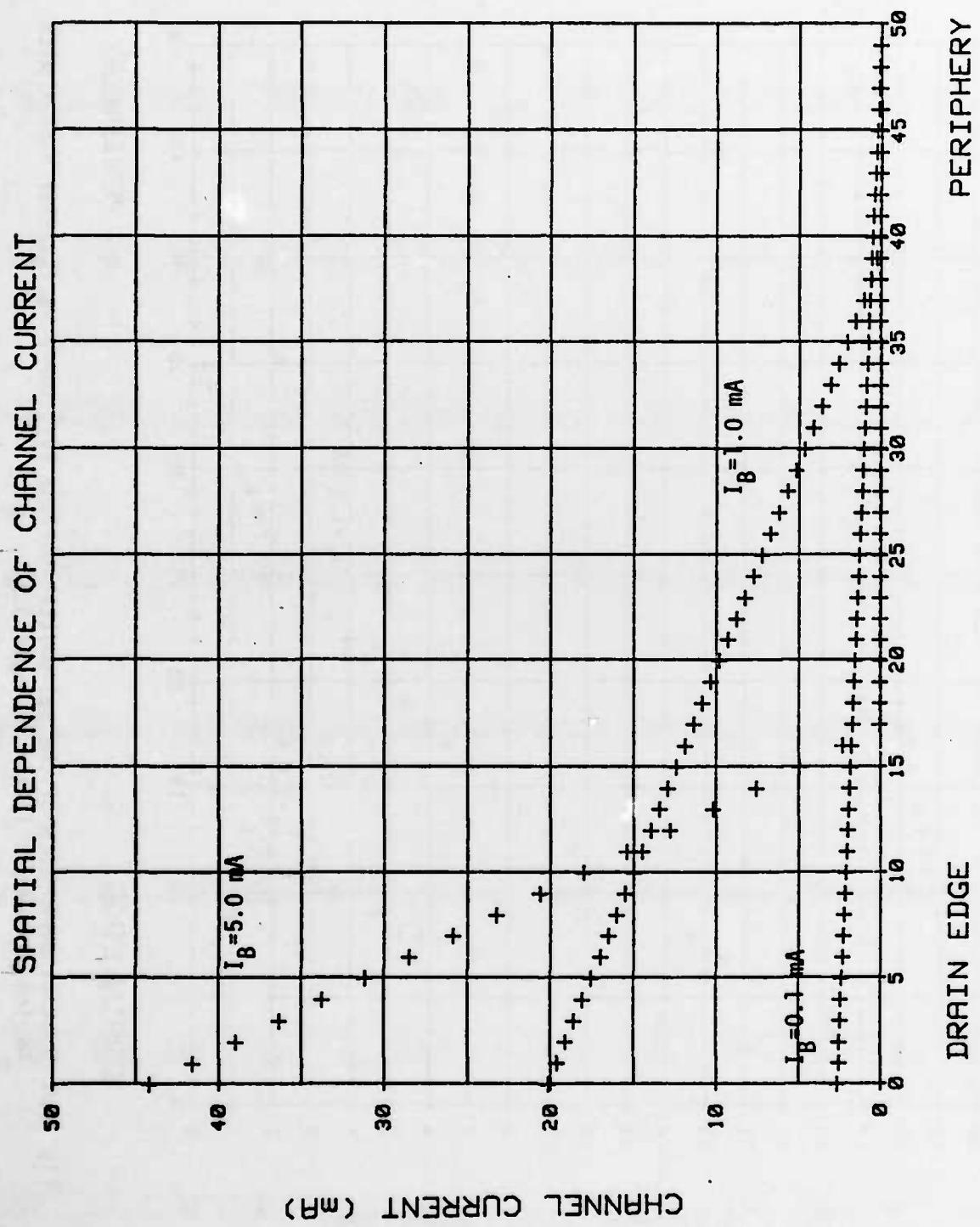


Fig. 3.7 Spatial dependence of channel current (I_{chX}) for a rectangular MOSBJT with device parameters listed in Table 3.1.

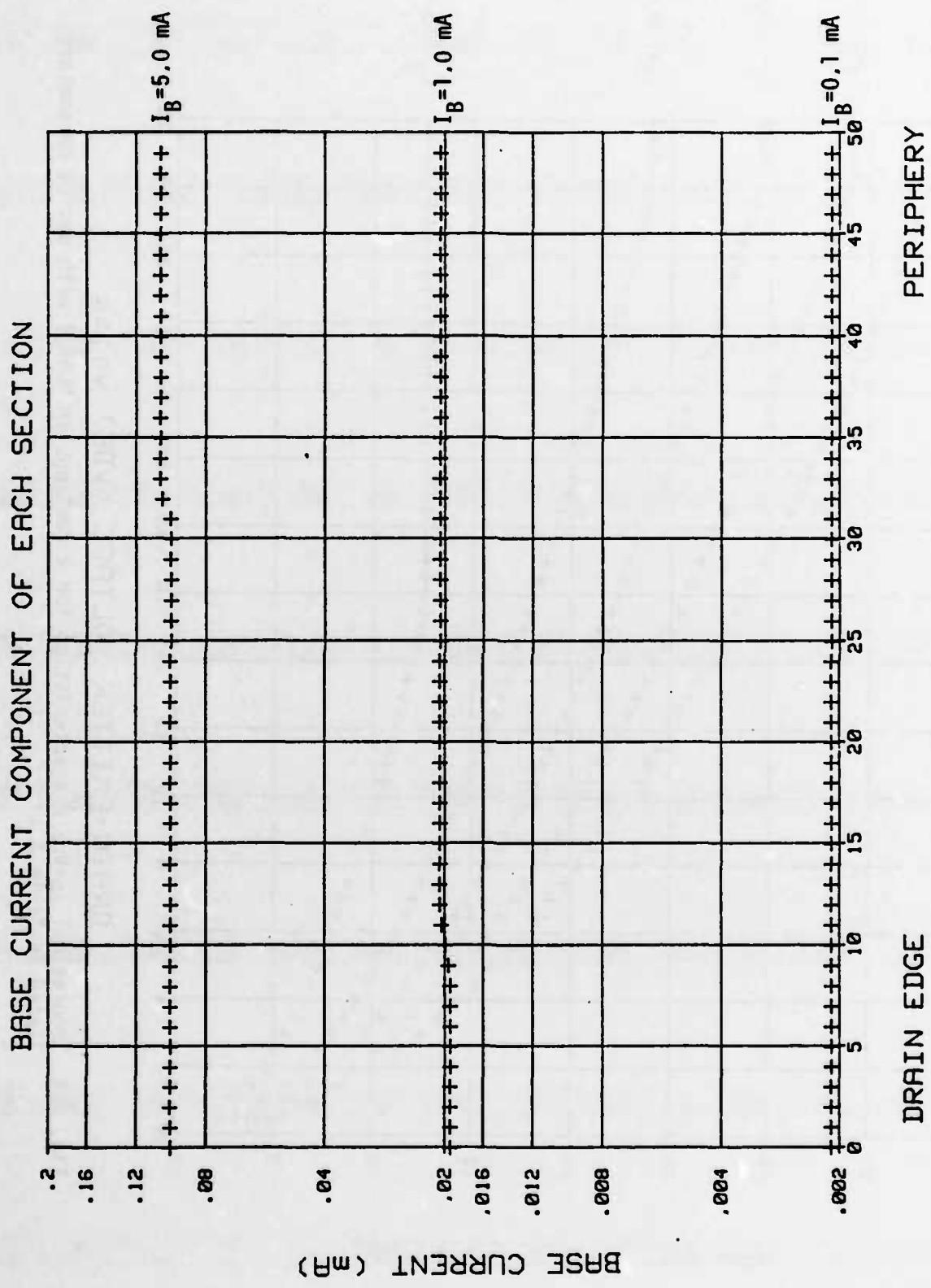
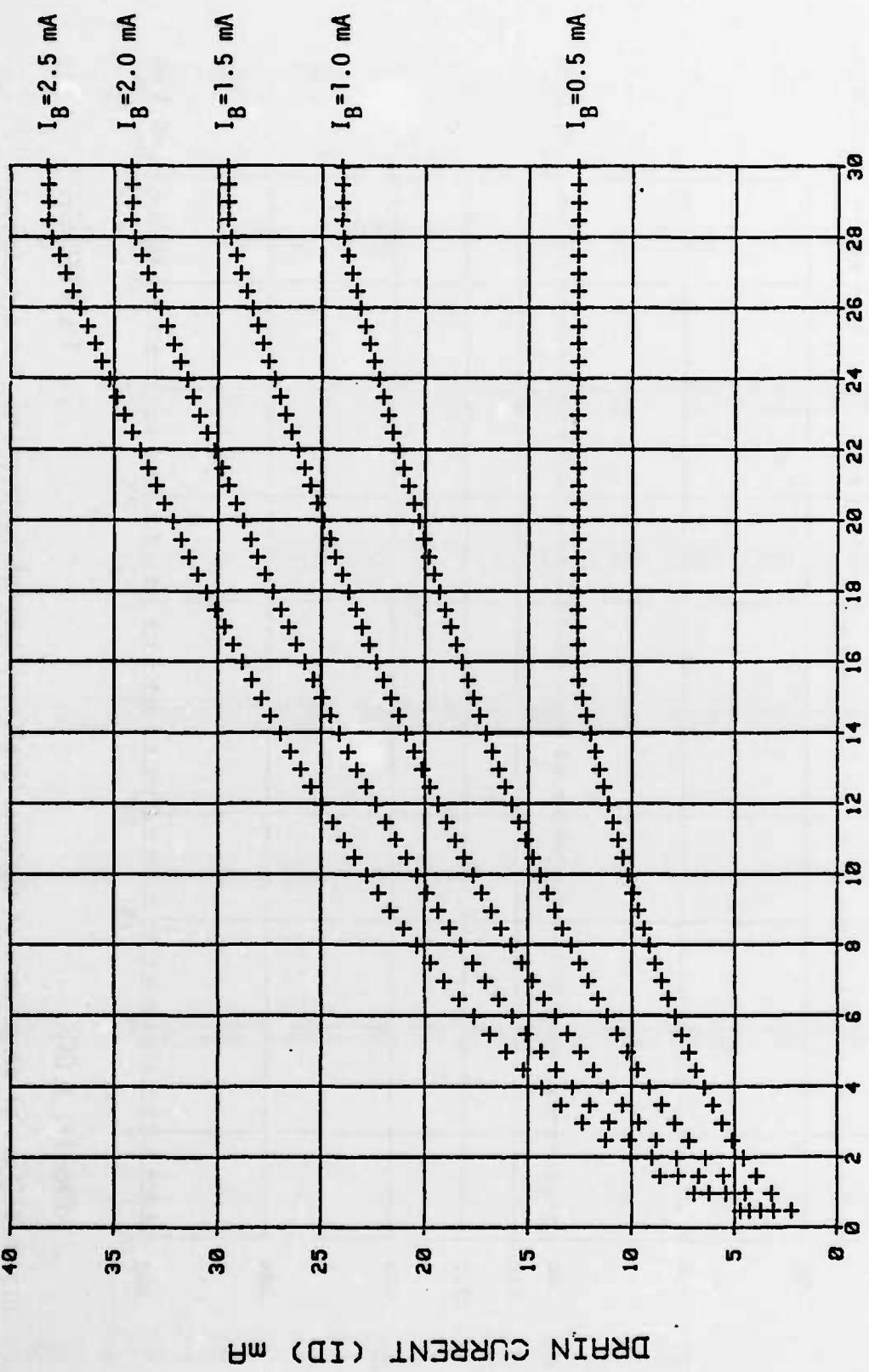


Fig. 3.8 Spatial dependence of the sectional base current contribution for a rectangular MOSBJT with device parameters listed in Table 3.1.

ID-V_{DE} CHARACTERISTICS OF THE RECTANGULAR MOSBJT



DRAIN-EMITTER VOLTAGE (V_{DE}) volts

Fig. 3.9 Theoretical I_D - V_{DE} characteristics for a rectangular MOSBJT with device parameters listed in Table 3.1.

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110
120
130
140
150
160
170
180
190
200
210 OPTION BASE 0
220 DIM Ic(200),Im(200),Vd(200),Vs(100),Ibi(200)
230 INTEGER N
240 ! THE MOSBJT OPERATING BIAS MUST BE SPECIFIED
250
260 Vg ... THE GATE VOLTAGE
270 Vde .. THE APPLIED DRAIN VOLTAGE
280 Vbe .. THE Emitter-Base JUNCTION BIAS
290 N ... THE NUMBER OF SECTIONS IN THE MODEL
300 Vg=20
310 Vde=10
320 Vbe=.40
330 N=100
340 CALL I_v_char(Vg,Vde,Vbe,N,Ic(*),Im(*),Vd(*),Ibi(*),Ibcal)
350 !
360 ! THE SUBROUTINE I_v_char RETURNS
370
380 Vd(*) .. THE ARRAY CONTAINING THE NODE VOLTAGES
390 Ic(*) .. THE ARRAY CONTAINING THE BJT COLLECTOR CURRENTS
400 Im(*) .. THE ARRAY CONTAINING THE MOSFET DRAIN CURRENTS
410 Ibi(*).. THE ARRAY CONTAINING THE BASE CURRENT FOR EACH SECTION
420 Ibcal .. THE TOTAL TERMINAL BASE CURRENT
430 Im(N) .. THE TERMINAL DRAIN CURRENT FOR THE MOSBJT
440 Vd(N+1). THE CALCULATED TERMINAL DRAIN VOLTAGE (VDCAL)
450 FOR L=1 TO N+1
460 PRINT Vd(L),Ic(L),Im(L)
470 NEXT L
480 END
490 !
500
510
520
530
540
550 I_V_char .... Given the operating bias of the MOSBJT
560 this program calculates the resultant
570 current and and voltage profile along
580 the channel and the terminal base and

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590 ! drain currents.
600
610 Wid ... This subprogram to calculate the average
620 width of a MOSFET circuit element.
630
640 Inca ..... This subprogram calculates the ratio
650 of the collector area of a particular
660 section to the total MOSBJT channel area
670
680 ****
690
700
710 SUB I_v_char(Vg,Vde,Vbe,INTEGER N,REAL Ic(*),Im(*),Vd(*),Ibi(*),Ibcal)
720 DIM Vs(200)
730 INTEGER Nmin,Nmax,L
740 !
750 GOSUB Modulea
760 GOSUB Moduleb
770 GOSUB Modulec
780 GOSUB Moduled
790 GOTO Fini
800
810 !!!!!!!!!!!!!!! MODULE A !!!!!!!
820
830
840 1. Define device parameters
850 2. Define device geometry
860 3. Define material constants
870 4. Define device bias
880 5. Calculate necessary intermediate parameters
890
900 !!!!!!!
910
920 Modulea: !
930
940 Define device parameters ....
950
960 Om - METAL WORK FUNCTION
970 Os - SILICON WORK FUNCTION
980 Eox - PERMETIVITY OF SiO2
990 Es - PERMETIVITY OF Si
1000 Tox - OXIDE THICKNESS
1010 Qss - SURFACE CHARGE DENSITY
1020 T - TEMPERATURE
1030 Na - SUBSTRATE DOPING
1040
1050
1060 Flg=0
1070 Om=4.10 | V
1080 Os=4.9 | V
1090 Eox=3.45E-11 | F/M
1100 Es=1.04E-10 | F/M
1110 Tox=1.2E-7 | METERS
1120 T=300 | DEG K
1130 Na=1.5E+16 | CM-3
1140 Qss=8.E-5 | C/M2
1150
1160
1170 Define device geometry ...
1180

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1190 | Length- LENGTH OF GATE
1200 | Width - WIDTH OF GATE
1210 | N - NUMBER OF SECTIONS
1220 |
1230 |
1240 |
1250 | Length=3.68E-3 | METERS
1260 | Width=2.96E-3 | METERS
1270 |
1280 |
1290 |
1300 | Specify BJT parameters ...
1310 |
1320 | AF - FORWARD ALPHA
1330 | AR - REVERSE ALPHA
1340 | IES -
1350 | ICS -
1360 | XB - BASE WIDTH
1370 |
1380 | Af=.962
1390 | Ar=.998
1400 | Ies=1.04E-8
1410 | Ics=1.002E-8
1420 |
1430 |
1440 |
1450 | CALCULATE INTERMEDIATE CONSTANTS
1460 |
1470 | Vfb - FLATBAND VOLTAGE
1480 | Vt - THRESHOLD VOLTAGE
1490 | D1 - SECTIONAL MOSFET LENGTH
1500 | Cox - OXIDE CAPACITANCE/AREA
1510 | Mu - MOBILITY
1520 | Op - ENERGY DIFFERENCE BETWEEN THE
1530 | INTRINSIC AND EXTRINSIC FERMI
1540 | LEVELS
1550 |
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1570 |
1580 | Cox=Eox/Tox
1590 | Vfb=0m-0s-Qss/Cox
1600 | Kb=1.38E-23
1610 | Q=1.6E-19
1620 | Mu=.05
1630 | Ni=1.45E+10
1640 | Op=-1*(Kb*T/Q)*LOG(Na/Ni)
1650 | D1=Length/N
1660 | Vt=Vfb+2*ABS(Op)+(1/Cox)*SQR(2*Es*Q*Na*1.0E+6*(2*ABS(Op)))
1670 |
1680 | IF THE MOSBJT IS BIASED INTO SATURATION VDE>VG-VT THEN VDE IS SET
1690 | TO VG-VT
1700 |
1710 | IF Vde>Vg-Vt THEN
1720 |   Vde=Vg-Vt
1730 |   PRINT "DEVICE SATURATED VDSAT=VG-VT = ",Vde
1740 | END IF
1750 |
1760 |
1770 |
1780 | PRINT THE ABOVE DATA

```

```

1790 !
1800     PRINT "OM=",Om
1810     PRINT "OS=",Os
1820     PRINT "EOX=",Eox
1830     PRINT "ES=",Es
1840     PRINT "TOX=",Tox
1850     PRINT "QSS=",Qss
1860     PRINT "T=",T,"K"
1870     PRINT "NA =",Na
1880     PRINT "LENGTH=",Length
1890     PRINT "WIDTH=",Width
1900     PRINT "NUMBER OF SECTIONS IS ",N
1910     PRINT "IES = ",Ies
1920     PRINT "ICS = ",Ics
1930     PRINT "AF = ",Af
1940     PRINT "OP = ",Op
1950     PRINT "VFB = ",Vfb
1960 !
1970 !
1980     RETURN
1990 !
2000 !
2010 !
2020 !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
2030 !
2040             MODULE B
2050 !
2060             Determine extent of channel cut-off
2070 !
2080 !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
2090 !
2100 Moduleb: !
2110 !
2120             Vbc .. The channel to emitter bias such that Ic=0
2130             Vchemin . The channel to emitter bias such that the
2140                 BJT connected to that node Ic is slightly
2150                 greater than 0. (Node is biased at the
2151                 onset of cutoff)
2152 !
2160             Lco ... Indicates the current section being
2170                 examined to determine if it is "active"
2180 !
2190 !
2200             Vbc=-(Kb*T/Q)+LOG(Af*Ies/Ics)
2210             Vchemin=Vbc+.01
2220             Vs(1)=Vchemin
2230             Nmin=1
2240             Nmax=N
2250 !
2260 Next_try: !
2270             Lco=(Nmin+Nmax)/2
2280             Ic(Lco)=0
2290             Im(Lco-1)=0
2300             Vd(Lco)=Vchemin
2310 !
2320 !
2330 Loop!: !
2340             FOR L=Lco TO N
2350             IF Q+(-Vd(L)+Vbe)/(Kb*T)<-100 THEN GOTO Aroundi

```

```

2360      Ic(L)=FNInca(Length,Width,N,L)*(Af*Ies*EXP(Q*Vbe/(Kb*T))-Ics*(EXP(
2361      (Q/(Kb*T))*(Vbe-Vd(L)))-1))
2370      GOTO Around2
2380  !
2390 Around1: !
2400      Ic(L)=FNInca(Length,Width,N,L)+Af*Ies*EXP(Q*Vbe/(Kb*T))
2410  !
2420 Around2: !
2430      Im(L)=Im(L-1)+Ic(L)
2440      IF (Vg-Vt+Vd(L))`2-(2*(Vg-Vt)*Vd(L)+Vd(L)`2+(2*Im(L)*D1)/(Mu*FNWid(
2450      (Width,Length,N,L)*Cox))<0 THEN GOTO Cut_off
2460      Vd(L+1)=Vg-Vt+Vd(L)-SOR((Vg-Vt+Vd(L))`2-(2*(Vg-Vt)*Vd(L)+Vd(L)`2+
2470      2*Im(L)*D1)/(Mu*FNWid(Width,Length,N,L)*Cox)))
2480      IF Vd(L+1)>Vde THEN GOTO Cut_off
2490      NEXT L
2500  !
2510  !
2520      Nmax=Lco
2530      IF Nmin=Nmax-1 THEN
2540      FOR L=1 TO Lco-1
2550      Ic(L)=0
2560      Im(L-1)=0
2570      Vd(L)=Vchemin
2580      NEXT L
2590      GOTO Found_it
2600      END IF
2610      GOTO Next_try
2620 Cut_off: !
2630      Nmin=Lco
2640      IF (Lco>=N) THEN
2650          DISP " ERROR !!!!! ENTIRE CHANNEL IS CUT OFF !"
2660          DISP " RERUN PROGRAM WITH A LARGER N "
2670          BEEP
2680          PAUSE
2690          END IF
2700      GOTO Next_try
2710  !
2720  !
2730  !
2740  !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
2750  !
2760  !
2770  !
2780  !
2790  !
2800  !
2810  !
2820  !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
2830  !
2840 ModuleC:   !
2850      K=1
2860 Loop2:   !
2870      FOR L=Lco TO N
2880      IF Q*(Vbe-Vd(L))/(Kb*T)<-100 THEN GOTO Around3
2890      Ic(L)=FNInca(Length,Width,N,L)*(Af*Ies*EXP(Q*Vbe/(Kb*T))-Ics*(EXP(
2900      Q*(-Vd(L)+Vbe)/(Kb*T))-1))
2910      GOTO Around4
2920 Around3: !

```

```

2920           Ic(L)=FNInca(Length.Width,N,L)+(Af*Ies*EXP(Q*Vbe/(Kb*T)))
2930 Around4: !
2940           Im(L)=Im(L-1)+Ic(L)
2950           IF (Vg-Vt+Vd(L))`2-(2*(Vg-Vt)+Vd(L)+Vd(L)`2+(2*Im(L)*D1)/(Mu*FNWid
(Width.Length,N,L)*Cox))<0 THEN GOTO Decrease
2960           Vd(L+1)=Vg-Vt+Vd(L)-SOR((Vg-Vt+Vd(L))`2-(2*(Vg-Vt)*Vd(L)+Vd(L)`2+
2*Im(L)*D1)/(Mu*FNWid(Width.Length,N,L)*Cox)))
2970           IF Vd(L+1)>Vde THEN GOTO Decrease
2980           NEXT L
2990 Adjust: !
3000 !
3010 !
3020           IF K=1 THEN
3030               Vsmin=Vs(K)
3040               Vsmax=Vs(K)
3050           END IF
3060           IF Flg=1 THEN GOTO Increase
3070           IF Vd(L+1)-Vde>0 THEN
3080               Flg=1
3090               GOTO Decrease
3100           END IF
3110           Vsmin=Vs(K)
3120           Vs(K+1)=SGN(Vd(L+1)-Vde)*(-1.)+Vs(K)
3130           Vd(Lco)=Vs(K+1)
3140           K=K+1
3150           GOTO Loop2
3160 Increase:!
3161           Vdcal=Vd(N+1)
3170           IF ABS(Vdcal-Vde)<.01 THEN GOTO Out
3180           IF SGN(Vdcal-Vde)>0 THEN GOTO Decrease
3190           Vsmin=Vs(K)
3200           GOTO New_guess
3210 Decrease:!
3220           Flg=1
3230           Vsmax=Vs(K)
3240 New_guess: !
3250           Vs(K+1)=(Vsmax+Vsmin)/2
3260           K=K+1
3270           Vd(Lco)=Vs(K)
3280           GOTO Loop2
3290 Out: !
3300             RETURN
3310 !
3320 !
3330 !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
3340 !
3350             MODULE D
3360 !
3370             CALCULATE IB
3380 !
3390 !!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!!
3400 !
3410 Moduled: !
3420           Ibcal=0
3430           FOR L=1 TO N
3440           IF ((-Vd(L+1)+Vbe)/(Kb*T))<-50 THEN GOTO Around5
3450           Ib=FNInca(Length.Width,N,L)*(Ies*(1-Af)*(EXP(Q*Vbe/(Kb*T))-1)+(Ics
-Af*Ies)+(EXP(Q*(-Vd(L+1)+Vbe)/(Kb*T))-1))
3460           GOTO 3490
3470 Around5: !

```

```
3480      Ib=FNIInca(Length,Width,N,L)*(Ies*(1-Af)*(EXP(Q*Vbe/(Kb*T))-1)-(Ics  
-Af*Ies))  
3490      Ibi(L)=Ib  
3500      Ibcal=Ibcal+Ib  
3510      NEXT L  
3520      RETURN  
3530 !  
3540 Fini:           !  
3550 !  
3560 SUBEND  
3570 !  
3580 !  
3590 !  
3600      DEF FNIInca(Length,Width,INTEGER N,INTEGER L)  
3610      F=N  
3620      Inca=1/F  
3630      RETURN Inca  
3640      FNEND  
3650 !  
3660      DEF FNWid(Length,Width,INTEGER N,INTEGER L)  
3670      Wid=Width  
3680      RETURN Wid  
3690      FNEND  
3700 !  
3710 !
```

END

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